



N-Channel Super Trench Power MOSFET

Description

The RM185N30DF uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

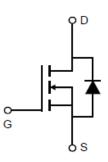
- V_{DS} =30V, I_D =185A $R_{DS(ON)}$ =1.1m Ω (typical) @ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)

 $R_{DS(ON)}$ =1.45m Ω (typical) @ V_{GS} =4.5V

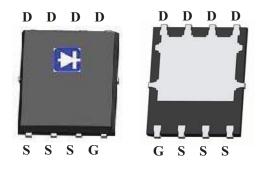
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



Schematic Diagram



Top View

Bottom View

100% UIS TESTED!

100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
185N30	RM185N30DF	DFN5X6-8L	1	1	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G S	±20	V
Drain Current-Continuous (Silicon Limited)	I _D	185	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	140	Α
Pulsed Drain Current (Package Limited)	I _{DM}	400	Α
Maximum Power Dissipation	P _D	95	W
Derating factor		0.76	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	1300	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{ heta JC}$	1.32	°C/W
--	----------------	------	------

Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.0	1.5	2.0	V
Dunin Course On Chata Desintance		V _{GS} =10V, I _D =95A	-	1.1	1.4	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =95A	-	1.45	1.8	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =95A	90	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ -45\/\/ -0\/	-	7350	8800	PF
Output Capacitance	Coss	V_{DS} =15V, V_{GS} =0V, F=1.0MHz	-	1930	2300	PF
Reverse Transfer Capacitance	C _{rss}	r-1.0lvinz	-	110	130	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	t _r	V_{DD} =15 V , I_{D} =95 A	-	10	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =3 Ω	-	51	-	nS
Turn-Off Fall Time	t _f		-	12	-	nS
Total Gate Charge	Qg	\/ -45\/ L -05A	-	125	140	nC
Gate-Source Charge	Q _{gs}	V_{DS} =15V, I_{D} =95A, V_{GS} =10V	-	18		nC
Gate-Drain Charge	Q_{gd}	V _{GS} -10V	-	13		nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =95A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	185	Α
Reverse Recovery Time	t _{rr}	$T_J = 25$ °C, $I_F = I_S$	-		38	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-		126	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V,L=0.5mH,Rg=25 Ω



RATING AND CHARACTERISTICS CURVES (RM185N30DF)

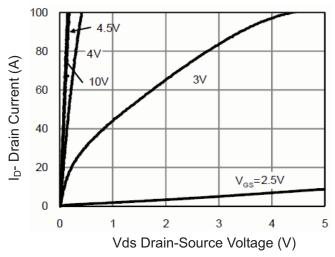


Figure 1 Output Characteristics

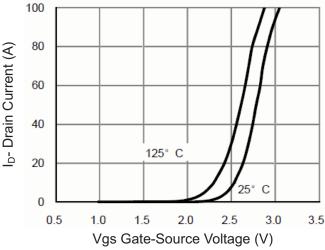


Figure 2 Transfer Characteristics

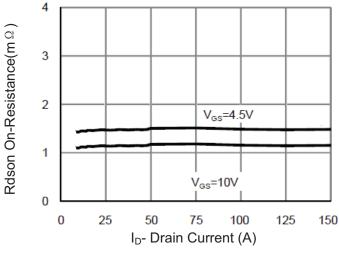


Figure 3 Rdson- Drain Current

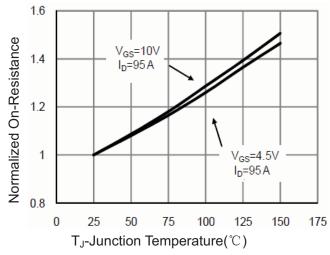


Figure 4 Rdson-Junction Temperature

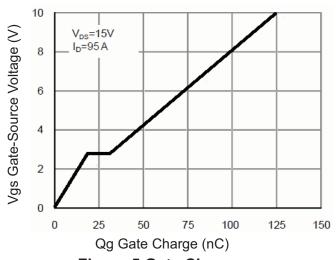


Figure 5 Gate Charge

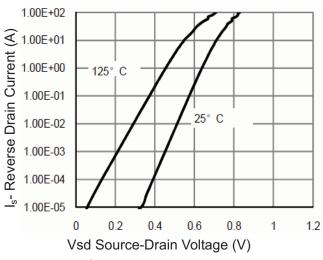


Figure 6 Source- Drain Diode Forward



RATING AND CHARACTERISTICS CURVES (RM185N30DF)

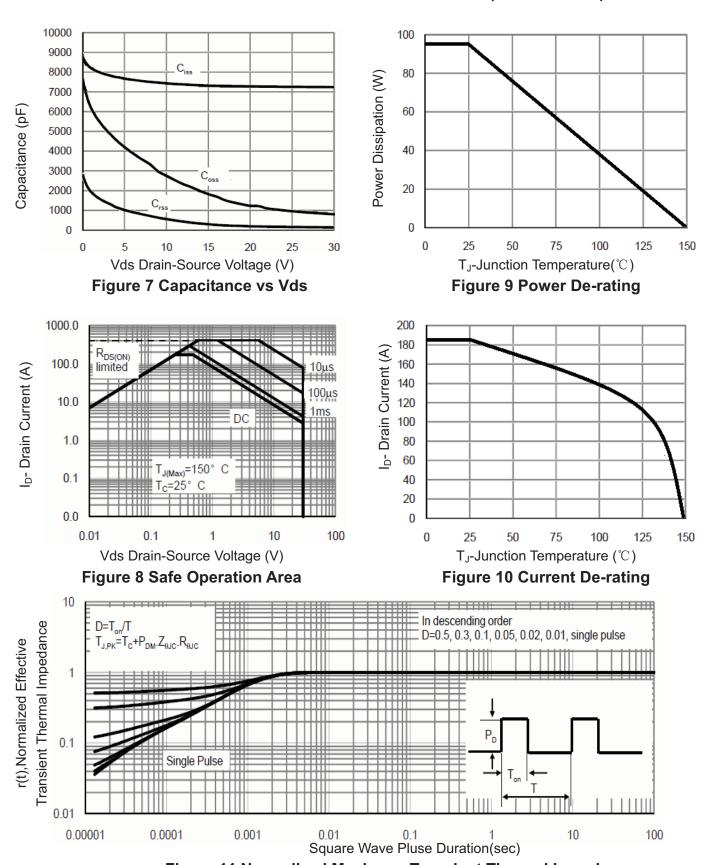
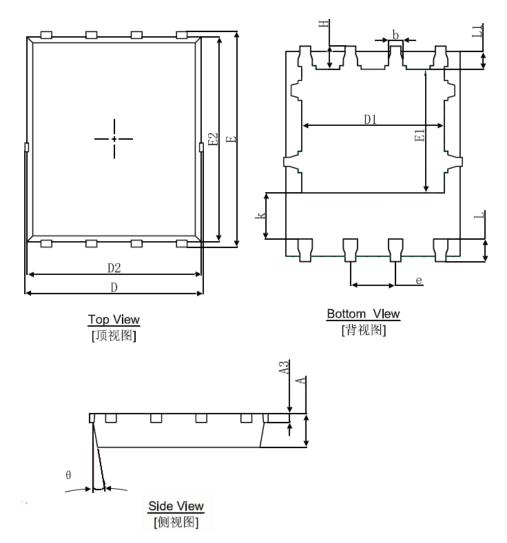


Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254	REF.	0.010REF.		
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.270TYP.		0.050TYP.		
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	8°	12°	8°	12°	



DISCLAIMER NOTICE

Rectron Inc reserves the right to make changes without notice to any product specification herein, to make corrections, modifications, enhancements or other changes. Rectron Inc or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies. Data sheet specifications and its information contained are intended to provide a product description only. "Typical" parameters which may be included on RECTRON data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. Rectron Inc does not assume any liability arising out of the application or use of any product or circuit.

Rectron products are not designed, intended or authorized for use in medical, life-saving implant or other applications intended for life-sustaining or other related applications where a failure or malfunction of component or circuitry may directly or indirectly cause injury or threaten a life without expressed written approval of Rectron Inc. Customers using or selling Rectron components for use in such applications do so at their own risk and shall agree to fully indemnify Rectron Inc and its subsidiaries harmless against all claims, damages and expenditures.

